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Kind regards,

Team Nexperia



# PDTB113ZT

PNP 500 mA, 50 V resistor-equipped transistor;  
R1 = 1 k $\Omega$ , R2 = 10 k $\Omega$

Rev. 3 — 23 September 2010

Product data sheet

## 1. Product profile

### 1.1 General description

500 mA PNP Resistor-Equipped Transistor (RET) in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package.

NPN complement: PDTD113ZT.

### 1.2 Features and benefits

- 500 mA output current capability
- Built-in bias resistors
- Simplifies circuit design
- Reduces component count
- Reduces pick and place costs
- $\pm 10\%$  resistor ratio tolerance
- AEC-Q101 qualified

### 1.3 Applications

- Digital application in automotive and industrial segments
- Control of IC inputs
- Cost-saving alternative for BC807 series in digital applications
- Switching loads

### 1.4 Quick reference data

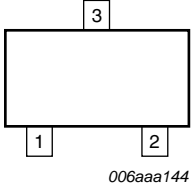
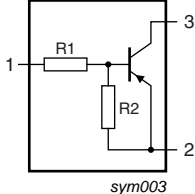
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>CEO</sub>	collector-emitter voltage	open base	-	-	-50	V
I <sub>O</sub>	output current		-	-	-500	mA
R1	bias resistor 1 (input)		0.7	1.0	1.3	k $\Omega$
R2/R1	bias resistor ratio		9	10	11	



## 2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	input (base)	 <p>006aaa144</p>	 <p>sym003</p>
2	GND (emitter)		
3	output (collector)		

## 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PDTB113ZT	-	plastic surface-mounted package; 3 leads	SOT23

## 4. Marking

Table 4. Marking codes

Type number	Marking code <sup>[1]</sup>
PDTB113ZT	*7W

- [1] \* = -: made in Hong Kong  
 \* = p: made in Hong Kong  
 \* = t: made in Malaysia  
 \* = W: made in China

## 5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter	-	-50	V
$V_{CEO}$	collector-emitter voltage	open base	-	-50	V
$V_{EBO}$	emitter-base voltage	open collector	-	-5	V
$V_I$	input voltage				
	positive		-	+5	V
	negative		-	-10	V
$I_O$	output current		-	-500	mA

**Table 5. Limiting values ...continued***In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	[1] -	250	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
T <sub>j</sub>	junction temperature		-	150	°C
T <sub>amb</sub>	ambient temperature		-65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

## 6. Thermal characteristics

**Table 6. Thermal characteristics**

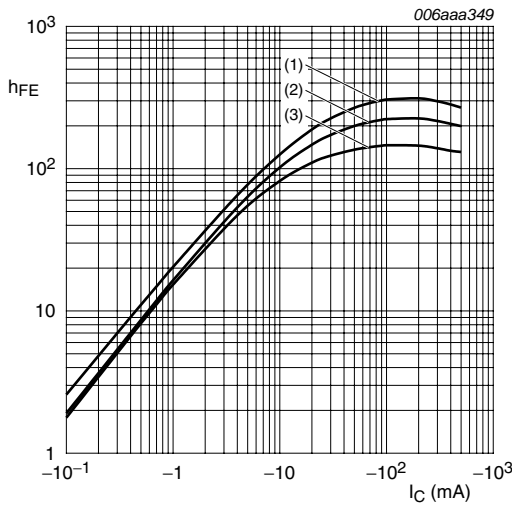
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air	[1] -	-	500	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

## 7. Characteristics

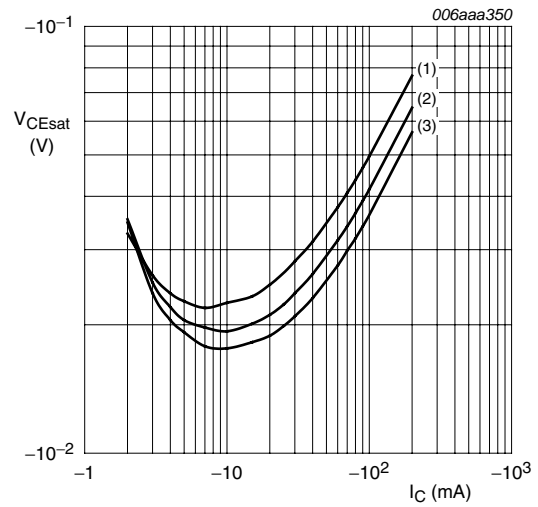
**Table 7. Characteristics***T<sub>amb</sub> = 25 °C unless otherwise specified.*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I <sub>CBO</sub>	collector-base cut-off current	V <sub>CB</sub> = -40 V; I <sub>E</sub> = 0 A	-	-	-100	nA
		V <sub>CB</sub> = -50 V; I <sub>E</sub> = 0 A	-	-	-100	nA
I <sub>CEO</sub>	collector-emitter cut-off current	V <sub>CE</sub> = -50 V; I <sub>B</sub> = 0 A	-	-	-0.5	μA
I <sub>EBO</sub>	emitter-base cut-off current	V <sub>EB</sub> = -5 V; I <sub>C</sub> = 0 A	-	-	-0.8	mA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = -5 V; I <sub>C</sub> = -50 mA	70	-	-	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = -50 mA; I <sub>B</sub> = -2.5 mA	-	-	-0.3	V
V <sub>I(off)</sub>	off-state input voltage	V <sub>CE</sub> = -5 V; I <sub>C</sub> = -100 μA	-0.3	-0.6	-1.0	V
V <sub>I(on)</sub>	on-state input voltage	V <sub>CE</sub> = -0.3 V; I <sub>C</sub> = -20 mA	-0.4	-0.8	-1.4	V
R1	bias resistor 1 (input)		0.7	1.0	1.3	k $\Omega$
R2/R1	bias resistor ratio		9	10	11	
C <sub>c</sub>	collector capacitance	V <sub>CB</sub> = -10 V; I <sub>E</sub> = i <sub>e</sub> = 0 A; f = 100 MHz	-	11	-	pF



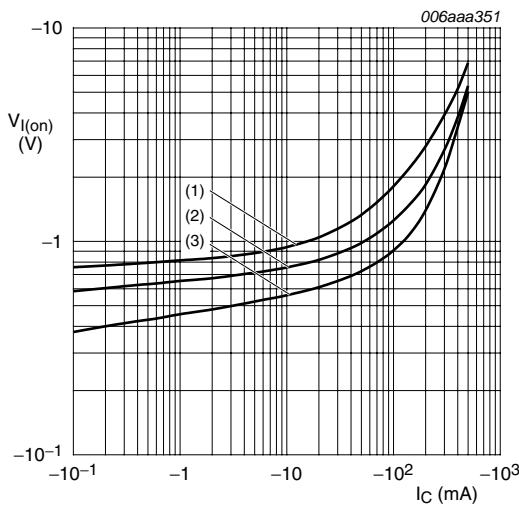
$V_{CE} = -5\text{ V}$   
 (1)  $T_{amb} = 100\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = -40\text{ °C}$

**Fig 1. DC current gain as a function of collector current; typical values**



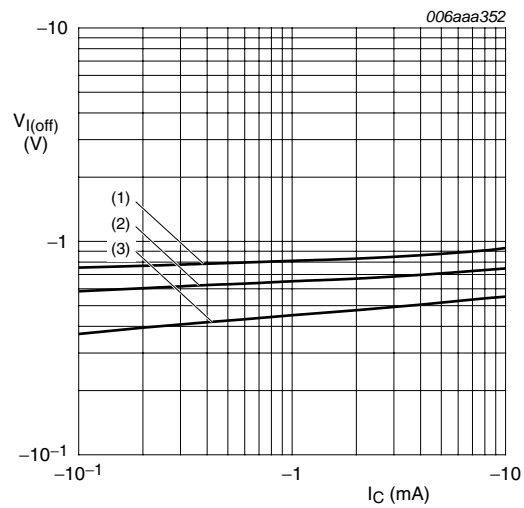
$I_C/I_B = 20$   
 (1)  $T_{amb} = 100\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = -40\text{ °C}$

**Fig 2. Collector-emitter saturation voltage as a function of collector current; typical values**



$V_{CE} = -0.3\text{ V}$   
 (1)  $T_{amb} = -40\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = 100\text{ °C}$

**Fig 3. On-state input voltage as a function of collector current; typical values**



$V_{CE} = -5\text{ V}$   
 (1)  $T_{amb} = -40\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = 100\text{ °C}$

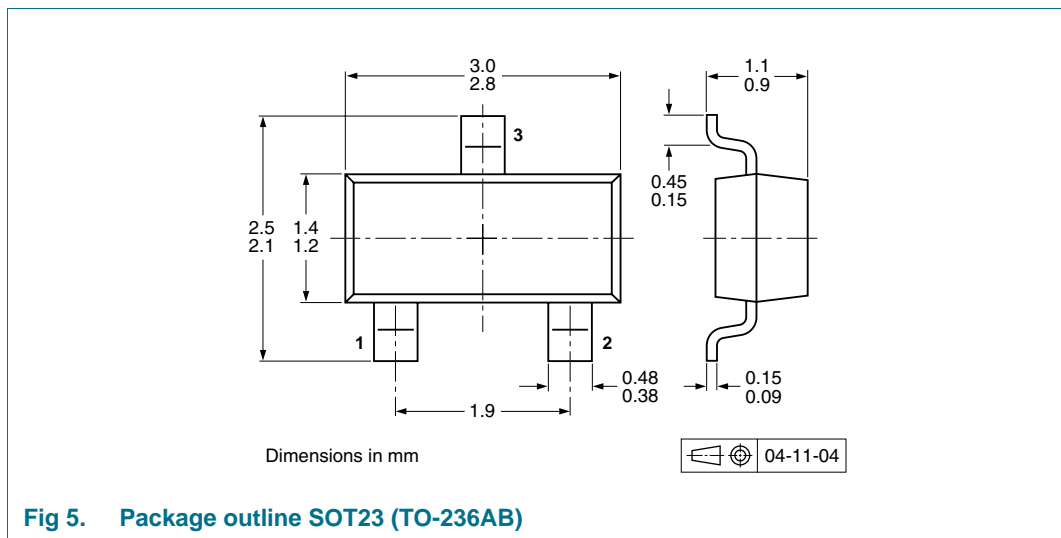
**Fig 4. Off-state input voltage as a function of collector current; typical values**

## 8. Test information

### 8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

## 9. Package outline



## 10. Packing information

**Table 8. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

Type number	Package	Description	Packing quantity	
			3000	10000
PDTB113ZT	SOT23	4 mm pitch, 8 mm tape and reel	-215	-235

[1] For further information and the availability of packing methods, see [Section 14](#).

### 11. Soldering

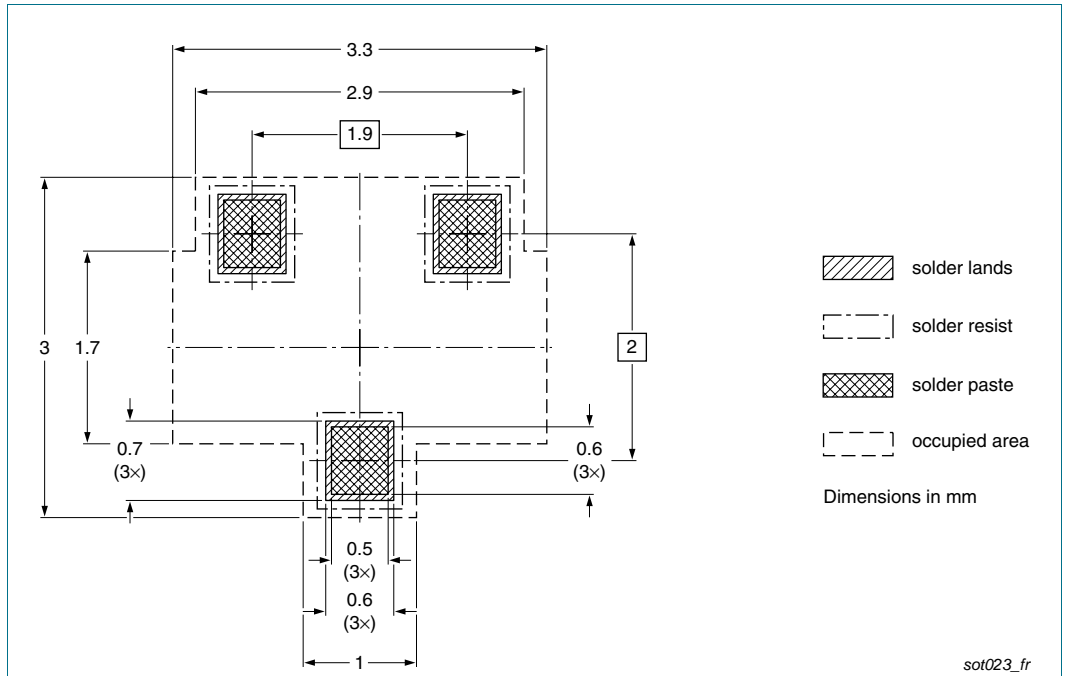


Fig 6. Reflow soldering footprint SOT23 (TO-236AB)

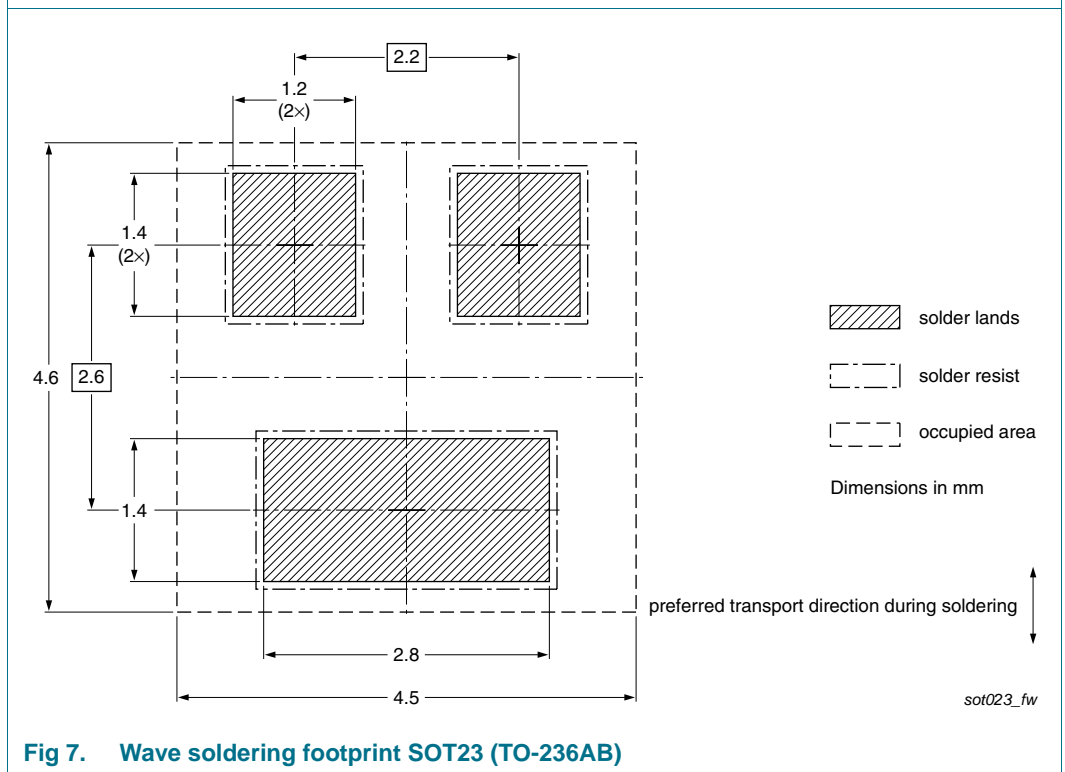


Fig 7. Wave soldering footprint SOT23 (TO-236AB)

## 12. Revision history

**Table 9.** Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PDTB113ZT v.3	20100923	Product data sheet	-	PDTB113Z_SER_2
Modifications:	<ul style="list-style-type: none"><li>• Type numbers PDTB113ZK and PDTB113ZS deleted.</li><li>• <a href="#">Table 7 “Characteristics”</a>: unit for <math>V_{CEsat}</math> changed from mV to V.</li><li>• <a href="#">Section 8 “Test information”</a>: added.</li><li>• <a href="#">Section 11 “Soldering”</a>: added.</li><li>• <a href="#">Section 13 “Legal information”</a>: updated.</li></ul>			
PDTB113Z_SER_2	20091116	Product data sheet	-	PDTB113Z_SER_1
PDTB113Z_SER_1	20050427	Product data sheet	-	-



## 13. Legal information

### 13.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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